

Attorney Docket No. US.03.036
USSN 10/667,648

REMARKS

Reconsideration of the above-identified application in view of the amendments above and remarks below is respectfully requested.

Claims 1 - 18 are currently before the Examiner. Claims 1 and 11-13 have been amended herein.

Claims 1-18 stand rejected under 35 U.S.C. 102(b) as being anticipated by Yasuda *et al.* (US Pat. No. 5,081,206). The rejection is respectfully traversed.

In response, applicants state that the present invention is directed to a process utilizing an alkali metal containing compound as a cure accelerator. Yasuda *et al.* is directed to an epoxy resin composition. The present application differs from Yasuda *et al.* in that the reference does not teach or suggest utilizing NaOH, or any alkali metal containing compound, as a cure accelerator in an epoxy resin composition for preparing a resin coated article. Yasuda *et al.* only disclose NaOH as an upstaging catalyst in the preparation of an epoxy resin or only use NaOH as a base in the preparation of an epoxy resin.

Specifically, in the specification, Yasuda *et al.* discloses generally the use of NaOH as a well-known fusion catalyst for the polyaddition reaction between an epoxy group and a phenolic hydroxyl group to prepare an epoxy resin (col. 7, lines 23-33). In examples 1 and 3 Yasuda *et al.* continually add a 48% solution of NaOH dropwise during the synthesis of the resin. However, it is apparent the dropwise addition of NaOH here is use of the compound as base and not use as a fusion catalyst. For curing agents and curing accelerators, Yasuda *et al.* states only generally that the amounts used varies and that, if desired, an accelerator may be utilized (col. 5, lines 59-63, col. 8, lines 3-6 and col. 10 lines 63-63). Yasuda *et al.* only discloses a specific curing agent, dicyandiamide, and a specific cure accelerator, 2-ethyl-4-methylimidazole, in examples 1 and 3.

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Therefore, the referenced does not teach or even suggest the use of NaOH or any other alkali metal compound as a cure accelerator as taught and claimed by claim 1 of the present invention. Claims 2-18 incorporate the limitations of claim 1 and are considered patentable for at least the same reasons as claim 1.

Claims 1 and 3-18 stand rejected under 35 U.S.C. 102(b) as being anticipated by Corley (US Pat. No. 4,503,200). The rejection is respectfully traversed.

Initially, applicants have amended claim 1 to further define the curing agent as containing an amine, amide or phenolic group, which curing agents which were utilized the examples of the present application. Corley only generally discloses alkali metal salts as suitable cure accelerators to be utilized in conjunction with polycarboxylic acid and polycarboxylic anhydride curing agents. Corley, however, also discloses as an essential feature of his invention the use of at least one "onium" compound as a curing accelerator. Corley does not teach or suggest the use of NaOH as a cure accelerator in conjunction with the curing agents of claim 1, as now amended, or that such use would result in resin coated articles having enhanced thermal properties such as improved resistance to elevated temperatures as desired, for example, in printed circuit board applications. Claims 3-18 incorporate the limitations of claim 1 and are considered patentable for at least the same reasons as claim 1.

Claims 1 and 3-18 stand rejected under 35 U.S.C. 102(b) as being anticipated by Allen (US Pat. No. 4,554,341). The rejection is respectfully traversed.

As with Corley, Allen discloses polycarboxylic acid and polycarboxylic anhydride curing agents, and additionally discloses halogenated acid anhydride curing agents. Also, as with Corley, Allen discloses as an essential feature, the use of at least one "onium" compound as a curing accelerator. Allen only generally discloses alkali metal salts as suitable cure "co-accelerators." Allen does not teach or suggest the use of alkali metal containing compounds as a cure accelerator utilized in conjunction with the curing agents of claim 1, as currently amended, or that this use would result in resin coated articles having enhanced thermal properties such as improved resistance to elevated temperatures as desired, for example, in printed circuit board

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applications. Claims 3-18 incorporate the limitations of claim 1 and are considered patentable for at least the same reasons as claim 1.

Claim 2 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Corley (US Pat. No. 4,503,200) or Allen (US Pat. No. 4,554,341). The rejection is respectfully traversed.

Referring to the discussion above regarding Corley and Allen, claim 2 is dependant upon and incorporates the limitations of claim 1 and is considered patentable for at least the same reasons as claim 1.

Claims 11-13 stand rejected under 35 U.S.C. 112, 2nd paragraph, as being indefinite. The rejection is respectfully traversed. In response, applicants have amended claims 11-13 to depend from claim 10, as suggested by the Examiner.

In light of the above amendments and remarks, it is respectfully submitted that the pending claims of the present application are in condition for allowance. If the Examiner has any questions or requires additional information, he is invited to contact the undersigned.

Respectfully submitted,



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